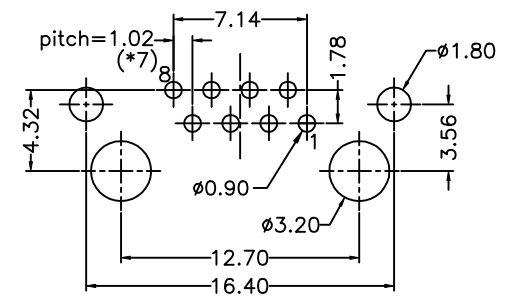
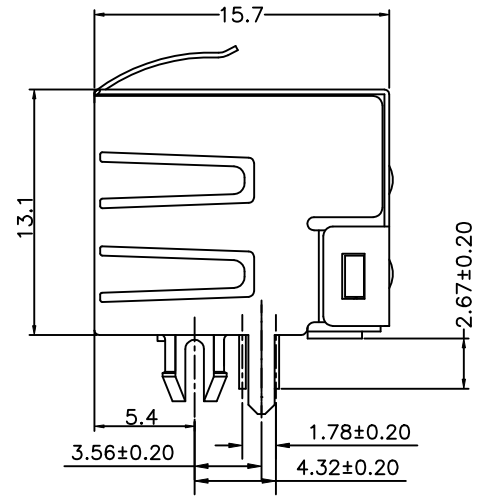
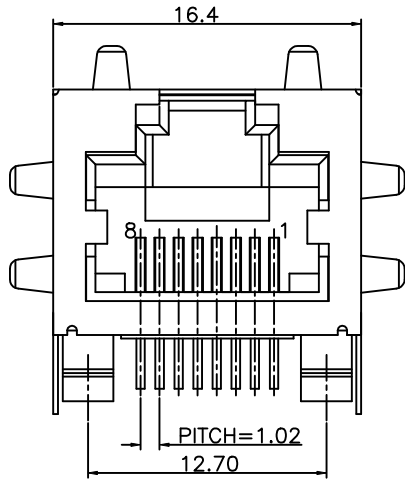


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



PCB (t=1.60mm) Layout  
Component Side Shown

**NOTES:**

**ELECTRICAL:**

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.
6. OPERATING: 750 CYCLES MIN.

**MECHANICAL:**

1. HOUSING MATERIAL : PBT+30%.G.F UL94V-0 COLOR-BLACK.
2. INSERT MATERIAL : PBT+30%GF UL94V-0 COLOR-BLACK.
3. BACK PLATE MATERIAL : PBT+30%GF COLOR-BLACK.
4. SHIELD MATERIAL : COPPER ALLOY 0.25mm THICKNESS PLATING NI.
5. CONTACT MATERIAL : PHOSPHOR BRONZE 0.35mm THICKNESS OR  $\phi$ 0.46mm.LEAD FREE.
6. PLATING : GOLD PLATING OVER NICKEL.
7. PCB RETENTION PRE-SOLDER : 1 LB MIN.
8. PCB RETENTION POST-SOLDER: 10 LBS MIN.

**ENVIRONMENTAL:**

1. STORAGE : -40°C TO +85°C.
2. OPERATION: 0°C TO 70°C.
3. WAVE SOLDERING TEMPERATURE: 230~250°C(3~5 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.  
CUL FILE NO. E163191

DOHS PART NUMBER: E 5J 8 8 - X X L O X X -L

0-NO.LED  
6-HS'G&SHIELD NO LED

PLATING:1-3u" 2-6u" 3-15u"  
4-30u" 5-50u"

A-TIN SHIELD STAMPED PIN  
B-NI SHIELD STAMPED PIN  
F-NI SHIELD ROUND PIN ( $\phi$ 0.46)

PBT+30%(A06-1490)

0-W/O SHIELD 1-NO TAB  
2-TOP TABS. 3-SIDE TABS.  
4-TOP TABS & SIDE TABS.

MM (INCH)		DFTO YANGLAN	DATE 05/25/05
TOLERANCES EXCEPT AS NOTED		CHKD JAKE	DATE 2006/9/25
		MFO	DATE
		APPV LUSHENQ	DATE 2006/5/25
MATERIAL :		MATERIAL :	
ANGLES ±		QTY :	
THIRD ANGLE PROJECTION		FINISH :	
		SCALE :	

FULL RISE ELECTRONIC CO., LTD			
TITLE RJ45 W/O LED JACK			
DRAWING NO. GE5J3A11-LC		SIZE A3	REV 0
/PART NO. SEE NOTE		DO NOT SCALE DRAWING	
SHEET 1		OF 1	